Title (en)

CONDUCTOR FRAME, PRINTED CIRCUIT BOARD WITH A CONDUCTOR FRAME AND A METHOD FOR PRODUCING A CONDUCTOR FRAME

Title (de)

LEITERBAHNRAHMEN, PLATINE MIT LEITERBAHNRAHMEN UND VERFAHREN ZUR HERSTELLUNG EINES LEITERBAHNRAHMENS

Title (fr)

CADRE A PISTES CONDUCTRICES, CARTE EQUIPEE D'UN TEL CADRE ET PROCEDE POUR LA FABRICATION DE CE DERNIER

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Application

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Abstract (en)

[origin: WO0007242A1] The invention relates to a conductor frame (1) comprising at least one integrated electronic circuit (4, 5), whereby the integrated electronic circuit (4, 5) is situated in the area of a main surface of the conductor frame (1). The inventive conductor frame (1) also comprises at least one signal line (9), whereby at least one electrically insulating plate (2, 2', 3, 3') and one electrically conductive earthed plate (14, 14') are arranged at least in sections between the integrated electronic circuit (4, 5) and the signal line (9). The invention also relates to a method for producing the inventive conductor frame (1).

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IPC 8 full level

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